



# BGA7351

**50 MHz to 500 MHz high linearity Si variable gain amplifier;  
28 dB gain range**

Rev. 3 — 11 June 2014

Product data sheet

## 1. Product profile

### 1.1 General description

The BGA7351 MMIC is a dual independently digitally controlled IF Variable Gain Amplifier (VGA) operating from 50 MHz to 500 MHz. Each IF VGA amplifies with a gain range of 28 dB and at its maximum gain setting delivers 16.5 dBm output power at 1 dB gain compression and a superior linear performance.

The BGA7351 Dual IF VGA is optimized for a differential gain error of less than  $\pm 0.1$  dB for accurate gain control and has a total integrated gain error of less than  $\pm 0.3$  dB. Moreover it meets the demanding phase error requirements for GSM. BGA7351 has less than  $3.0^\circ$  phase error over the full gain range of 28 dB.

The gain controls of each amplifier are separate digital gain-control word, which is provided externally through two sets of 5 bits.

The BGA7351 is housed in a 32 pins 5 mm  $\times$  5 mm leadless HVQFN32 package.

### 1.2 Features and benefits

- Dual independent digitally controlled 28 dB gain range VGAs, with 5-bit control interface
- 50 MHz to 500 MHz frequency operating range
- Gain step size:  $1 \text{ dB} \pm 0.1 \text{ dB}$
- 22 dB power gain
- Fast gain stage switching capability
- 16.5 dBm output power at 1 dB gain compression
- 46 dBm third order intercept point
- Constant third order intercept point over output power
- $-85 \text{ dBc}$  second harmonic level
- Excellent noise figure of 6 dB
- 5 V single supply operation with power-down control
- Logic-level shutdown control pin reduces supply current
- Excellent ESD protection at all pins
- Moisture sensitivity level 1
- Unconditionally stable
- Excellent differential integrated gain and phase error
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)



### 1.3 Applications

- Compatible with GSM / W-CDMA / WiMAX / LTE base-station infrastructure / multi carrier systems
- Multi channel receivers
- General use for ADC driver applications

### 1.4 Quick reference data

**Table 1. Quick reference data**

$A\_EN = "1"; B\_EN = "1"$  (VGA enabled). Typical values at  $V_{CC} = 5$  V;  $I_{CC} = 280$  mA;  
Tuned for  $f_{IF} = 172$  MHz;  $B = 60$  MHz;  $T_{case} = 25$  °C; Differential input resistance matched to  $150 \Omega$ ;  
Differential output resistance matched to  $200 \Omega$ ; unless otherwise specified; see [Section 11](#)  
“Application information”.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$V_{CC}$	supply voltage	$V_{CC(A)} + V_{CC(B)}$	4.75	5	5.25	V	
$I_{CC}$	supply current	$I_{CC(A)} + I_{CC(B)}$					
		$A\_EN = "0"; B\_EN = "0"$	-	3	5	mA	
		$A\_EN = "1"; B\_EN = "1"$	-	280	300	mA	
$G_p$	power gain	maximum gain	[1]	21	22	23	dB
		minimum gain	[2]	-7	-6	-5	dB
$R_{i(dif)}$	differential input resistance		120	150	180	Ω	
$R_{o(dif)}$	differential output resistance		140	180	220	Ω	
NF	noise figure	maximum gain	[1]	-	6	7	dB
		increased rate per gain step	-	0.8	1		dB
IP3 <sub>O</sub>	output third-order intercept point	gain step 14	[3][4]	-	46	-	dBm
$P_{L(1dB)}$	output power at 1 dB gain compression	upper 5 gain steps	[1][5]	-	16.5	-	dBm
$\alpha_{2H}$	second harmonic level	gain step 14	[4][6]	-	-85	-	dBc
$E_{G(dif)}$	differential gain error		-	$\pm 0.1$	-		dB
$E_{\phi(dif)}$	differential phase error	upper 12 dB gain range	-	1.0	-	deg	
		per gain step (for all consecutive gain steps)	-	0.5	-	deg	

[1] Maximum gain; gain code = 00000.

[2] Minimum gain; gain code = 11100.

[3]  $P_L = 2$  dBm per tone; spacing = 2 MHz ( $f_1 = 171$  MHz;  $f_2 = 173$  MHz)

[4] Gain code = 01110.

[5] Gain code = 00000, 00001, 00010, 00011, 00100.

[6]  $P_L = 2$  dBm one tone ( $f = 86$  MHz;  $f_{meas} = 172$  MHz)

## 2. Pinning information

### 2.1 Pinning

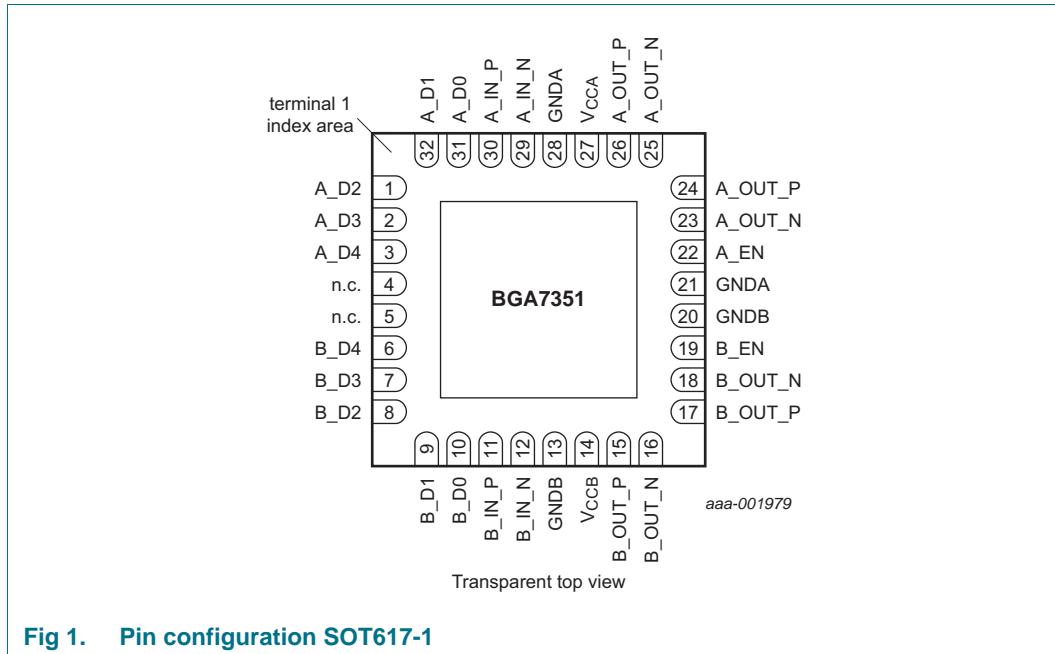


Fig 1. Pin configuration SOT617-1

### 2.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
A_D2	1	MSB – 2 for gain control interface of channel A
A_D3	2	MSB – 1 for gain control interface of channel A
A_D4	3	MSB for gain control interface of channel A
n.c.	4	not connected [1]
n.c.	5	not connected [1]
B_D4	6	MSB for gain control interface of channel B
B_D3	7	MSB – 1 for gain control interface of channel B
B_D2	8	MSB – 2 for gain control interface of channel B
B_D1	9	LSB + 1 for gain control interface of channel B
B_D0	10	LSB for gain control interface of channel B
B_IN_P	11	channel B positive input [2]
B_IN_N	12	channel B negative input [2]
GND_B	13, 20	ground for channel B
V_CCB	14	supply voltage for channel B
B_OUT_P	15, 17	channel B positive output [2]
B_OUT_N	16, 18	channel B negative output [2]
B_EN	19	power enable pin for channel B
GND_A	21, 28	ground for channel A

**Table 2. Pin description ...continued**

Symbol	Pin	Description
A_EN	22	power enable pin for channel A
A_OUT_N	23, 25	channel A negative output <a href="#">[2]</a>
A_OUT_P	24, 26	channel A positive output <a href="#">[2]</a>
V <sub>CCA</sub>	27	supply voltage for channel A
A_IN_N	29	channel A negative input <a href="#">[2]</a>
A_IN_P	30	channel A positive input <a href="#">[2]</a>
A_D0	31	LSB for gain control interface of channel A
A_D1	32	LSB + 1 for gain control interface of channel A
GND	GND paddle	RF ground and DC ground <a href="#">[3]</a>

[1] Pin to be left open.

[2] Each channel should be independently enabled with logic HIGH and disabled with logic LOW.

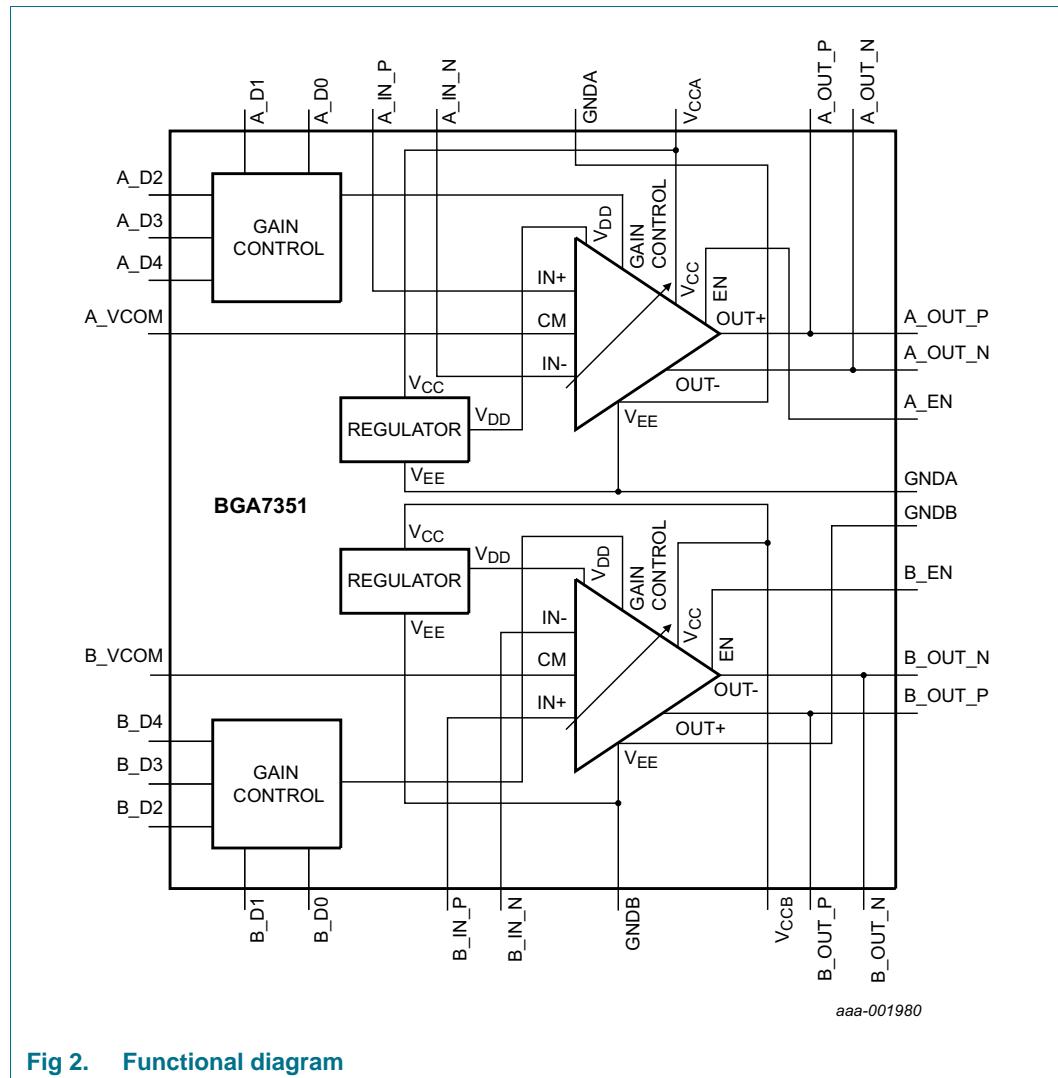
[3] The center metal base of the SOT617-1 also functions as heatsink for the VGA.

### 3. Ordering information

**Table 3. Ordering information**

Type number	Package		
	Name	Description	Version
BGA7351	HVQFN32	plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 × 5 × 0.85 mm	SOT617-1

## 4. Functional diagram



## 5. Enable control

**Table 4. Enable / disable control settings**

Mode	Function description	Mode description	Enable		V <sub>EN</sub> (V)		I <sub>EN</sub> (μA)	
			A_EN	B_EN	Min	Max	Min	Max
A_EN, B_EN	VGA function off	disable	"0"	"0"	0	0.8	-	1
A_EN, B_EN	VGA in operating mode	enable	"1"	"1"	1.6	5.25	-	1

## 6. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC(A)}$	supply voltage (A)		[1]	-	6 V
$V_{CC(B)}$	supply voltage (B)		[1]	-	6 V
$V_{AEN}$	voltage on pin A_EN		-0.6	+6	V
$V_{BEN}$	voltage on pin B_EN		-0.6	+6	V
$V_{AD0}$	voltage on pin A_D0		-0.6	+6	V
$V_{AD1}$	voltage on pin A_D1		-0.6	+6	V
$V_{AD2}$	voltage on pin A_D2		-0.6	+6	V
$V_{AD3}$	voltage on pin A_D3		-0.6	+6	V
$V_{AD4}$	voltage on pin A_D4		-0.6	+6	V
$V_{BD0}$	voltage on pin B_D0		-0.6	+6	V
$V_{BD1}$	voltage on pin B_D1		-0.6	+6	V
$V_{BD2}$	voltage on pin B_D2		-0.6	+6	V
$V_{BD3}$	voltage on pin B_D3		-0.6	+6	V
$V_{BD4}$	voltage on pin B_D4		-0.6	+6	V
$V_{AIN}$	voltage on pin A_IN		-0.6	+6	V
$V_{BIN}$	voltage on pin B_IN		-0.6	+6	V
$P_{i(RF)}$	RF input power		-	20	dBm
$T_{case}$	case temperature		-40	+85	°C
$T_j$	junction temperature		-	150	°C
$V_{ESD}$	electrostatic discharge voltage	Human Body Model (HBM); According JEDEC standard 22-A114E	-	4000	V
		Charged Device Model (CDM); According JEDEC standard 22-C101B	-	2000	V
		Machine Model (MM); According JEDEC standard 22-A115	-	400	V

[1] Caution: All digital pins may not exceed  $V_{CC}$  as the internal ESD circuit can be damaged. To prevent this it is recommended that  $V_{AEN}$  and  $V_{BEN}$  are limited to a maximum of 5 mA.

## 7. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-case)}$	thermal resistance from junction to case	$T_{case} = 85^{\circ}\text{C}$ ; $V_{CC} = 5\text{ V}$ ; $I_{CC} = 280\text{ mA}$	7	K/W

## 8. Static characteristics

**Table 7. Characteristics**

$A\_EN = "1"; B\_EN = "1"$  (both channels enabled). Typical values at  $V_{CC} = 5$  V;  $T_{case} = 25$  °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage	$V_{CC(A)} + V_{CC(B)}$	4.75	5	5.25	V
$I_{CC}$	supply current	$I_{CC(A)} + I_{CC(B)}$				
		$A\_EN = "0"; B\_EN = "0"$	-	3	5	mA
		$A\_EN = "1"; B\_EN = "1"$	-	280	300	mA
$V_{IH}$	HIGH-level input voltage		[1]	1.6	-	V
$V_{IL}$	LOW-level input voltage		[1]	-	-	V
$P$	power dissipation		-	1.4	1.6	W

[1] Voltage on the control pins.

## 9. Dynamic characteristics

**Table 8. Characteristics**

$A\_EN = "1"; B\_EN = "1"$  (VGA enabled). Typical values at  $V_{CC} = 5$  V;  $I_{CC} = 280$  mA; Tuned for  $f_{IF} = 172$  MHz;  $B = 60$  MHz;  $T_{case} = 25$  °C; Differential input resistance matched to  $150\ \Omega$ ; Differential output resistance matched to  $200\ \Omega$ ; unless otherwise specified; see [Section 11 "Application information"](#).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$G_p$	power gain	maximum gain	[1]				
		$f = 50$ MHz; $B = 30$ MHz	-	22.5	-	dB	
		$f = 172$ MHz; $B = 60$ MHz	21	22	23	dB	
		$f = 250$ MHz; $B = 60$ MHz	-	21.5	-	dB	
		$f = 450$ MHz; $B = 100$ MHz	-	21.5	-	dB	
		minimum gain	[2]				
		$f = 50$ MHz; $B = 30$ MHz	-	-5.5	-	dB	
		$f = 172$ MHz; $B = 60$ MHz	-7	-6	-5	dB	
		$f = 250$ MHz; $B = 60$ MHz	-	-6.5	-	dB	
		$f = 450$ MHz; $B = 100$ MHz	-	-8	-	dB	
$\Delta G_{adj}$	gain adjustment range		[1]	-	28	-	dB
$G_{step}$	gain step		-	1	-		
$G_{flat}$	gain flatness		[1]	-	$\pm 0.5$	-	dB
$E_{G(dif)}$	differential gain error		-	$\pm 0.1$	-	dB	
$E_{G(itg)}$	integrated gain error	upper 12 dB gain range	-	$\pm 0.2$	-	dB	
		full gain range	-	$\pm 0.3$	-	dB	
$E_{\phi(dif)}$	differential phase error	upper 12 dB gain range	-	1.0	-	deg	
		per gain step (for all consecutive gain steps)	-	0.5	-	deg	
		full gain range	-	3.0	-	deg	
$t_{s(step)G}$	gain step settling time	per 1.5 dB of steady state	-	5	15	ns	
		per 0.1 dB of steady state	-	20	40	ns	

**Table 8. Characteristics ...continued**

*A\_EN = "1"; B\_EN = "1" (VGA enabled). Typical values at  $V_{CC} = 5$  V;  $I_{CC} = 280$  mA; Tuned for  $f_{IF} = 172$  MHz;  $B = 60$  MHz;  $T_{case} = 25$  °C; Differential input resistance matched to  $150 \Omega$ ; Differential output resistance matched to  $200 \Omega$ ; unless otherwise specified; see [Section 11 "Application information"](#).*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$\Delta t_{d(\text{grp})}$	group delay time variation	$B = 30$ MHz	-	86	-	ps	
$t_{pu}$	power-up time		-	-	1	μs	
$R_{i(\text{dif})}$	differential input resistance		120	150	180	Ω	
$R_{o(\text{dif})}$	differential output resistance		140	180	220	Ω	
$\alpha_{\text{isol(ch-ch)}}$	isolation between channels	$f \leq 250$ MHz	50	-	-	dB	
		$250$ MHz $< f < 400$ MHz	47	-	-	dB	
		$400$ MHz $\leq f \leq 500$ MHz	45	-	-	dB	
CMRR	common-mode rejection ratio		40	-	-	dB	
IP3 <sub>O</sub>	output third-order intercept point	gain step 14	[3]				
		$f = 50$ MHz	[4]	-	47	-	dBm
		$f = 172$ MHz	[5]	-	46	-	dBm
		$f = 250$ MHz	[6]	-	41	-	dBm
		$f = 450$ MHz	[7]	-	34	-	dBm
		upper 5 gain steps	[8]				
		$f = 50$ MHz	[4]	-	48	-	dBm
		$f = 172$ MHz	[5]	-	44	-	dBm
		$f = 250$ MHz	[6]	-	41	-	dBm
		$f = 450$ MHz	[7]	-	33	-	dBm
IP2 <sub>O</sub>	output second-order intercept point	upper 5 gain steps	[8]				
		$f = 50$ MHz	[9]	-	78	-	dBm
		$f = 172$ MHz	[10]	-	73	-	dBm
		$f = 250$ MHz	[11]	-	65	-	dBm
$P_{L(1\text{dB})}$	output power at 1 dB gain compression	upper 5 gain steps	[8]				
		$f = 50$ MHz	-	16.8	-	-	dBm
		$f = 172$ MHz	-	16.5	-	-	dBm
		$f = 250$ MHz	-	15.8	-	-	dBm
		$f = 450$ MHz	-	15.1	-	-	dBm

**Table 8. Characteristics ...continued**

$A\_EN = "1"$ ;  $B\_EN = "1"$  (VGA enabled). Typical values at  $V_{CC} = 5$  V;  $I_{CC} = 280$  mA;  
 Tuned for  $f_{IF} = 172$  MHz;  $B = 60$  MHz;  $T_{case} = 25$  °C; Differential input resistance matched to  $150 \Omega$ ;  
 Differential output resistance matched to  $200 \Omega$ ; unless otherwise specified; see [Section 11](#)  
["Application information"](#).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\alpha_{2H}$	second harmonic level	gain step 14	[3]			
		$P_L = 2$ dBm, $f = 172$ MHz	[12]	-	-85	-
		$P_L = 5$ dBm, $f = 172$ MHz	[13]	-	-82	-
		$P_L = 2$ dBm, $f = 450$ MHz	[14]	-	-67	-
		$P_L = 5$ dBm, $f = 450$ MHz	[15]	-	-64	-
		upper 5 gain steps	[8]			
		$P_L = 2$ dBm, $f = 172$ MHz	[12]	-	-83	-
		$P_L = 5$ dBm, $f = 172$ MHz	[13]	-	-80	-
		$P_L = 2$ dBm, $f = 450$ MHz	[14]	-	-59	-
		$P_L = 5$ dBm, $f = 450$ MHz	[15]	-	-54	-
NF	noise figure	maximum gain	[1]	-	6	7
		increase rate per gain step	-	0.8	1	dB

[1] Maximum gain; gain code = 00000.

[2] Minimum gain; gain code = 11100.

[3] Gain code = 01110.

[4]  $P_L = 2$  dBm per tone; spacing = 2 MHz ( $f_1 = 49$  MHz;  $f_2 = 51$  MHz)

[5]  $P_L = 2$  dBm per tone; spacing = 2 MHz ( $f_1 = 171$  MHz;  $f_2 = 173$  MHz)

[6]  $P_L = 2$  dBm per tone; spacing = 2 MHz ( $f_1 = 249$  MHz;  $f_2 = 251$  MHz)

[7]  $P_L = 2$  dBm per tone; spacing = 2 MHz ( $f_1 = 449$  MHz;  $f_2 = 451$  MHz)

[8] Gain code = 00000, 00001, 00010, 00011, 00100.

[9]  $P_L = 2$  dBm per tone ( $f_1 = 24$  MHz;  $f_2 = 74$  MHz;  $f_{meas} = 50$  MHz)

[10]  $P_L = 2$  dBm per tone ( $f_1 = 82$  MHz;  $f_2 = 90$  MHz;  $f_{meas} = 172$  MHz)

[11]  $P_L = 2$  dBm per tone ( $f_1 = 120$  MHz;  $f_2 = 130$  MHz;  $f_{meas} = 250$  MHz)

[12]  $P_L = 2$  dBm one tone ( $f = 86$  MHz;  $f_{meas} = 172$  MHz)

[13]  $P_L = 5$  dBm one tone ( $f = 86$  MHz;  $f_{meas} = 172$  MHz)

[14]  $P_L = 2$  dBm one tone ( $f = 225$  MHz;  $f_{meas} = 450$  MHz)

[15]  $P_L = 5$  dBm one tone ( $f = 225$  MHz;  $f_{meas} = 450$  MHz)

**Table 9. Gain control**

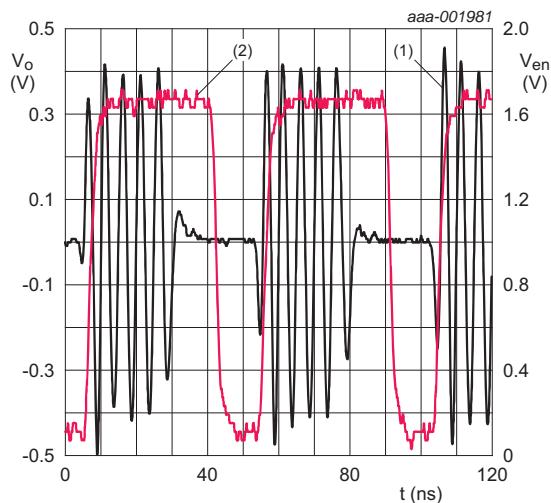
gain step	input to either A_D0 to A_D4 pins or B_D0 to B_D4 pins	nominal power gain (dB)
0	00000	22
1	00001	21
2	00010	20
3	00011	19
4	00100	18
5	00101	17
6	00110	16
7	00111	15
8	01000	14
9	01001	13
10	01010	12
11	01011	11
12	01100	10
13	01101	9
14	01110	8
15	01111	7
16	10000	6
17	10001	5
18	10010	4
19	10011	3
20	10100	2
21	10101	1
22	10110	0
23	10111	-1
24	11000	-2
25	11001	-3
26	11010	-4
27	11011	-5
28	11100	-6
-	> 11100	-6

## 10. Moisture sensitivity

**Table 10. Moisture sensitivity level**

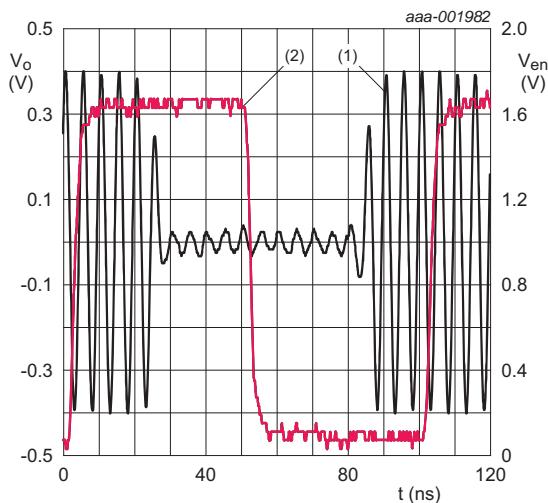
Test methodology	Class
JESD-22-A113	1

## 11. Application information



(1)  $V_o$   
 (2)  $V_{en}$

Fig 3. Enable time response



(1)  $V_o$   
 (2)  $V_{en}$

Fig 4. Gain step response from min. to max. gain

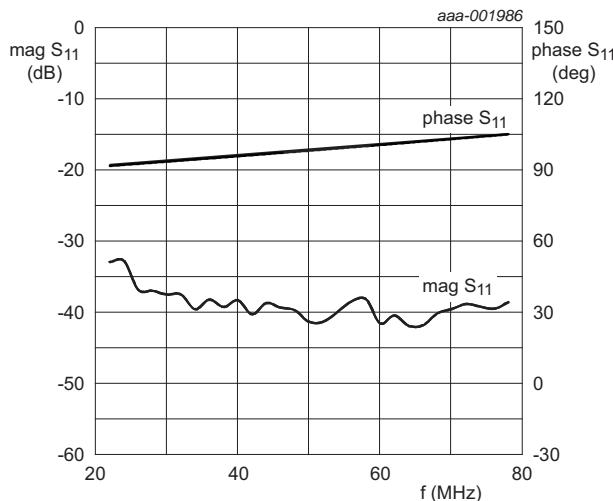


Fig 5.  $S_{11}$  as a function of frequency

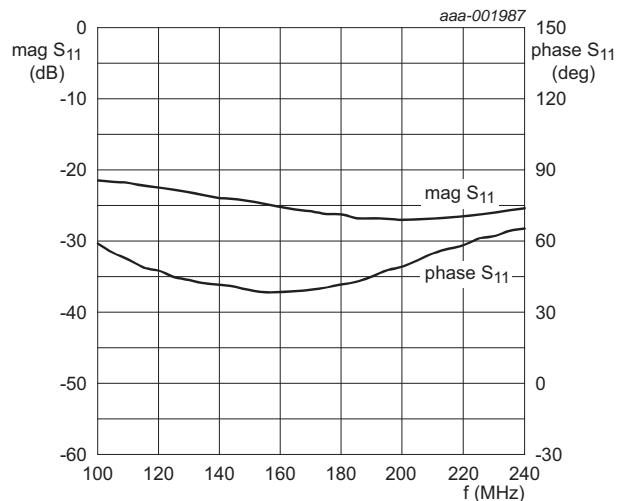
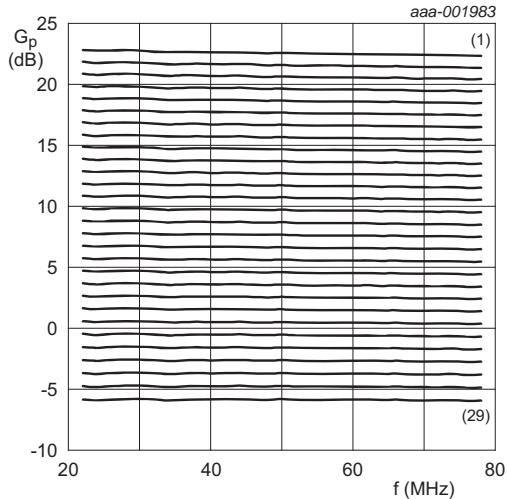
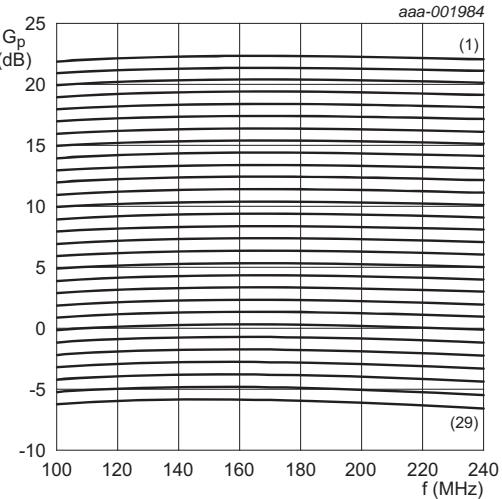


Fig 6.  $S_{11}$  as a function of frequency



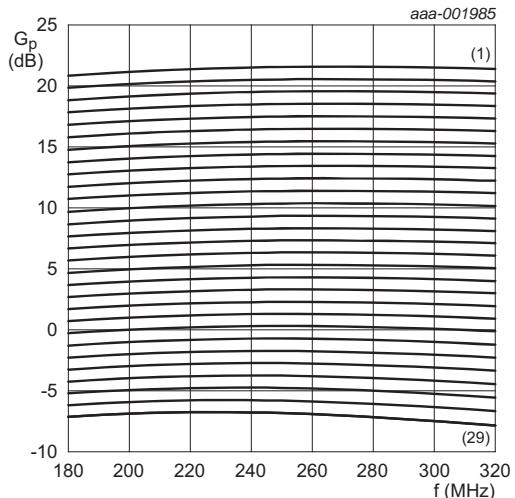
Tuned for  $f_{IF} = 50$  MHz;  $P_L = 5$  dBm; step size 1 dB.  
 (1) gain step 0 (maximum gain)  
 (29) gain step 28 (minimum gain)

**Fig 7. Power gain as a function of frequency**



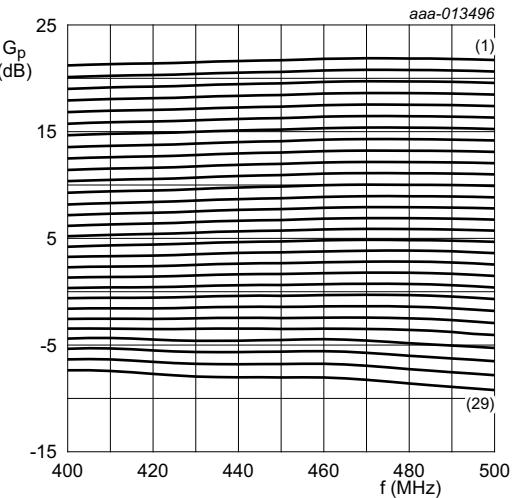
Tuned for  $f_{IF} = 172$  MHz;  $P_L = 5$  dBm; step size 1 dB.  
 (1) gain step 0 (maximum gain)  
 (29) gain step 28 (minimum gain)

**Fig 8. Power gain as a function of frequency**



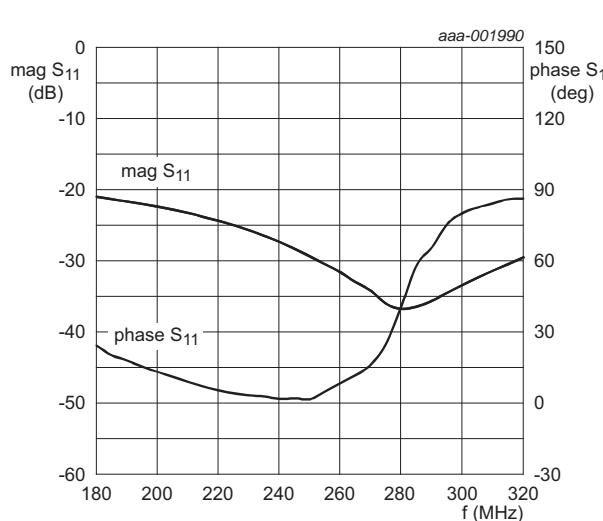
Tuned for  $f_{IF} = 250$  MHz;  $P_L = 5$  dBm; step size 1 dB.  
 (1) gain step 0 (maximum gain)  
 (29) gain step 28 (minimum gain)

**Fig 9. Power gain as a function of frequency**



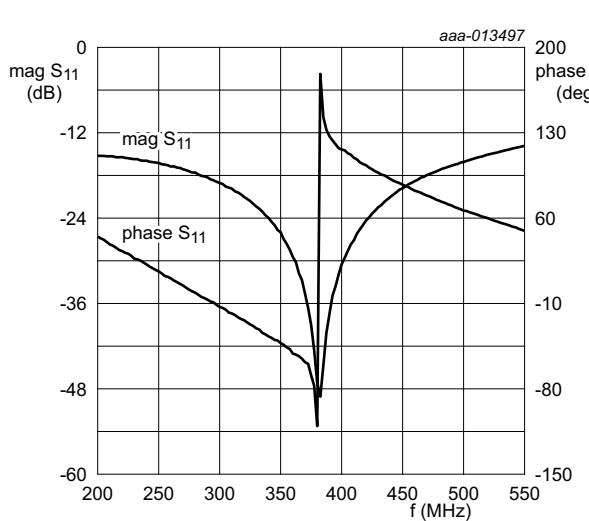
Tuned for  $f_{IF} = 450$  MHz;  $P_L = 5$  dBm; step size 1 dB.  
 (1) gain step 0 (maximum gain)  
 (29) gain step 28 (minimum gain)

**Fig 10. Power gain as a function of frequency**



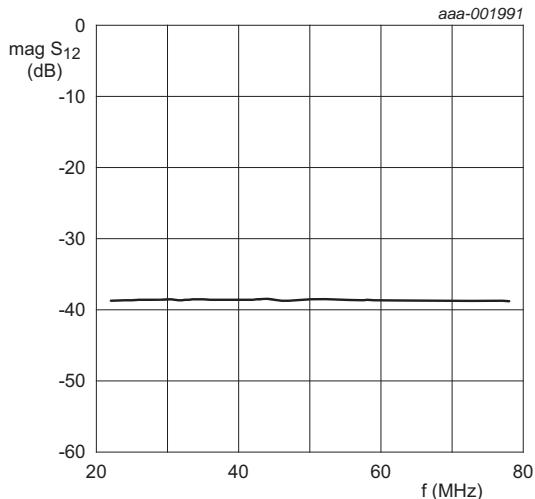
Tuned for  $f_{IF} = 250$  MHz; measured at gain step 0 (maximum gain).

**Fig 11.  $S_{11}$  as a function of frequency**



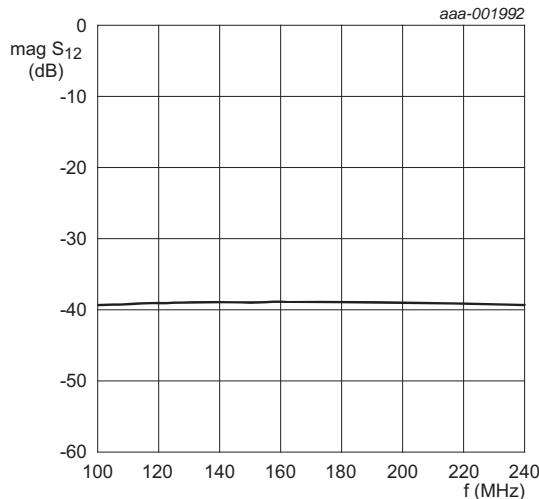
Tuned for  $f_{IF} = 450$  MHz; measured at gain step 0 (maximum gain).

**Fig 12.  $S_{11}$  as a function of frequency**



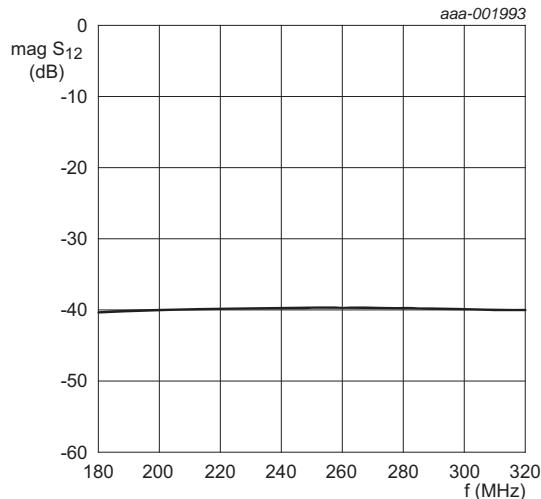
Tuned for  $f_{IF} = 50$  MHz; measured at gain step 0 (maximum gain).

**Fig 13.  $S_{12}$  as a function of frequency**



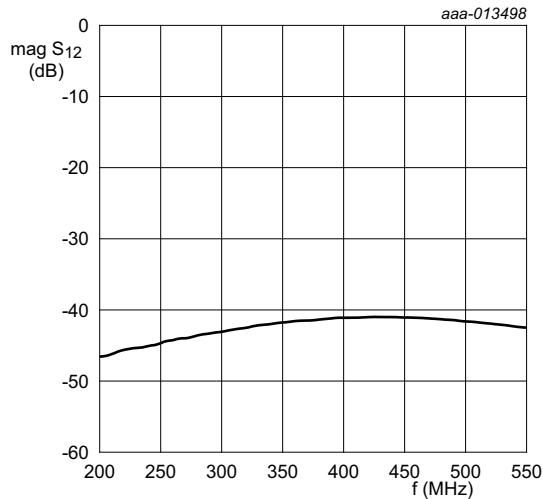
Tuned for  $f_{IF} = 172$  MHz; measured at gain step 0 (maximum gain).

**Fig 14.  $S_{12}$  as a function of frequency**



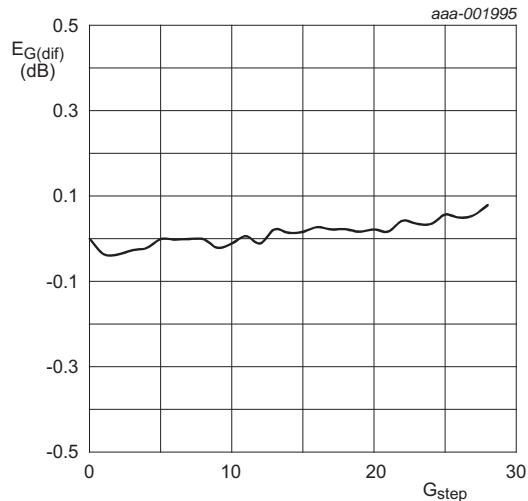
Tuned for  $f_{IF} = 250$  MHz; measured at gain step 0 (maximum gain).

Fig 15.  $S_{12}$  as a function of frequency



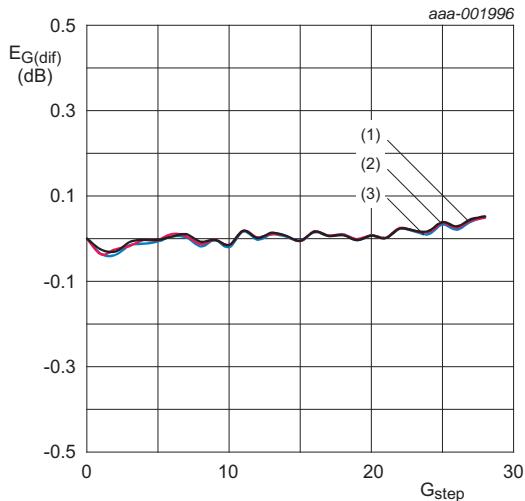
Tuned for  $f_{IF} = 450$  MHz; measured at gain step 0 (maximum gain).

Fig 16.  $S_{12}$  as a function of frequency



Tuned for  $f_{IF} = 50$  MHz.

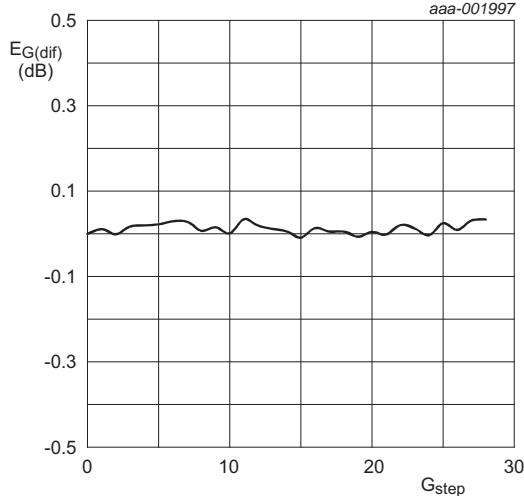
Fig 17. Differential gain error as a function of gain step



Tuned for  $f_{IF} = 172$  MHz.

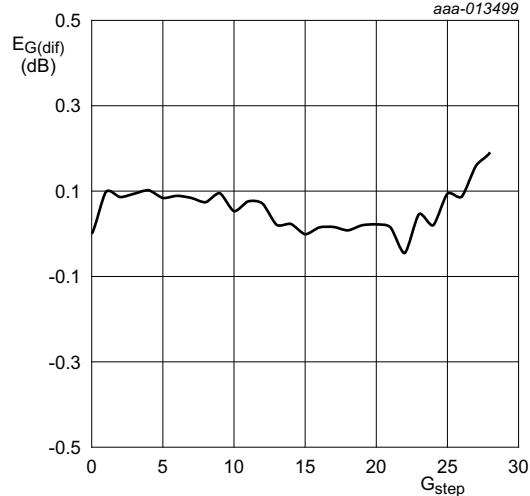
- (1)  $T_{amb} = -40$  °C
- (2)  $T_{amb} = +25$  °C
- (3)  $T_{amb} = +85$  °C

Fig 18. Differential gain error as a function of gain step



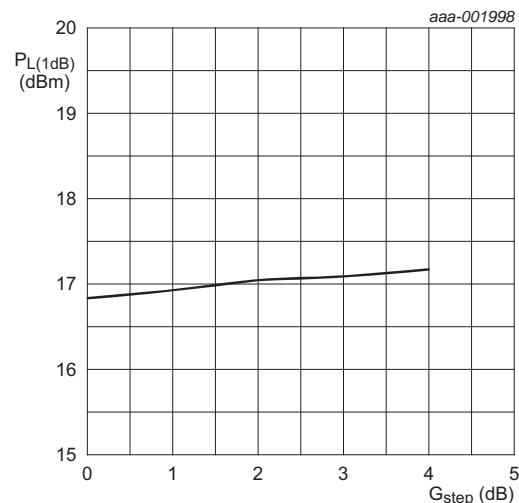
Tuned for  $f_{I_F} = 250$  MHz.

**Fig 19. Differential gain error as a function of gain step**



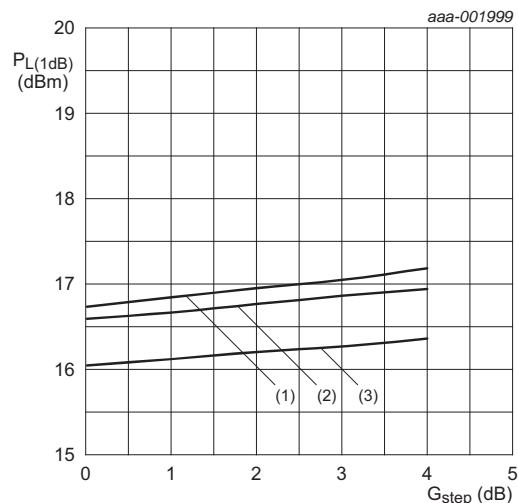
Tuned for  $f_{I_F} = 450$  MHz.

**Fig 20. Differential gain error as a function of gain step**



Tuned for  $f_{I_F} = 50$  MHz.

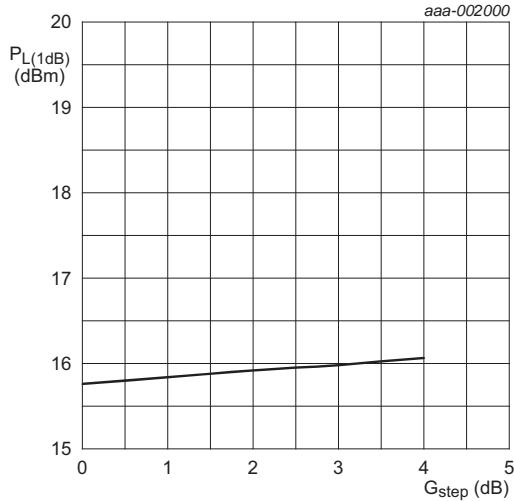
**Fig 21. output power at 1 dB gain compression as a function of gain step**



Tuned for  $f_{I_F} = 172$  MHz.

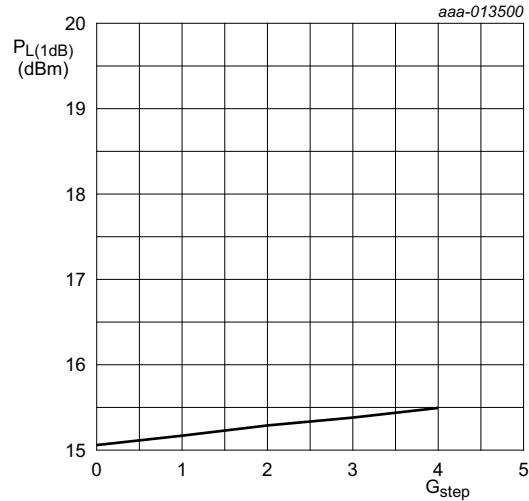
- (1)  $T_{amb} = -40$  °C
- (2)  $T_{amb} = +25$  °C
- (3)  $T_{amb} = +85$  °C

**Fig 22. output power at 1 dB gain compression as a function of gain step**



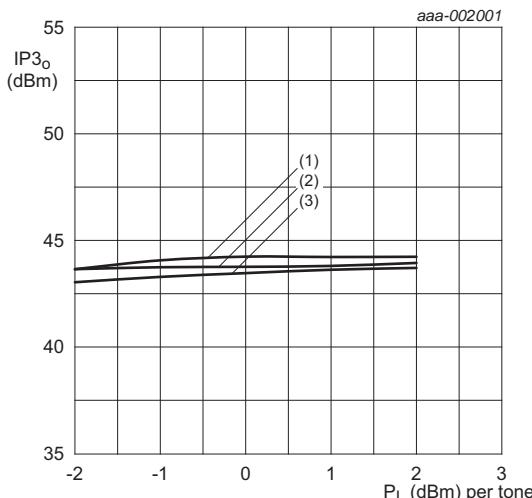
Tuned for  $f_{IF} = 250$  MHz.

**Fig 23. output power at 1 dB gain compression as a function of gain step**



Tuned for  $f_{IF} = 450$  MHz.

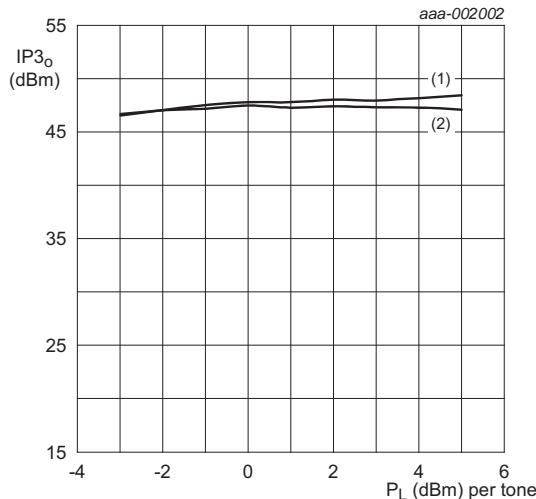
**Fig 24. output power at 1 dB gain compression as a function of gain step**



Tuned for  $f_{IF} = 172$  MHz; measured at gain step 0 (maximum gain).

- (1)  $T_{amb} = -40^\circ C$
- (2)  $T_{amb} = +25^\circ C$
- (3)  $T_{amb} = +85^\circ C$

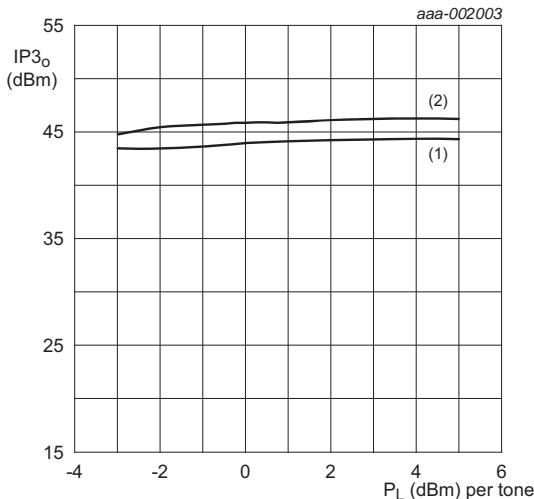
**Fig 25. Output third order intercept point as a function of output power per tone**



Tuned for  $f_{IF} = 50$  MHz.

- (1) gain step 0
- (2) gain step 14

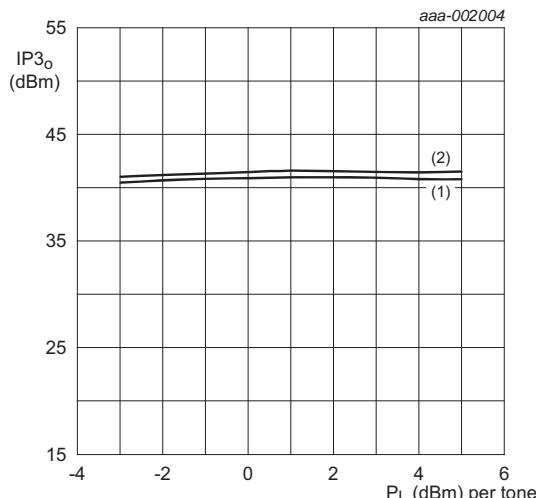
**Fig 26. Output third order intercept point as a function of output power per tone**



Tuned for  $f_{IF} = 172$  MHz.

- (1) gain step 0
- (2) gain step 14

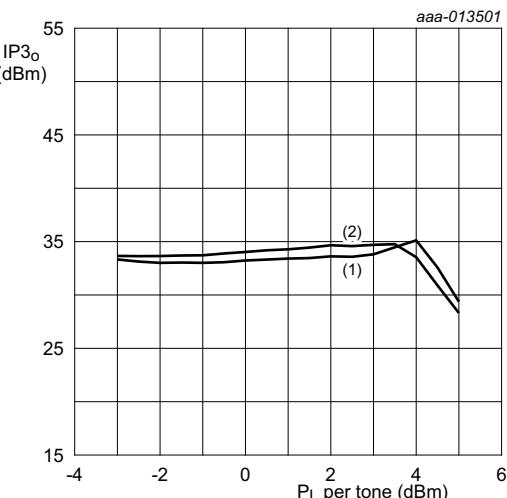
**Fig 27. Output third order intercept point as a function of output power per tone**



Tuned for  $f_{IF} = 250$  MHz.

- (1) gain step 0
- (2) gain step 14

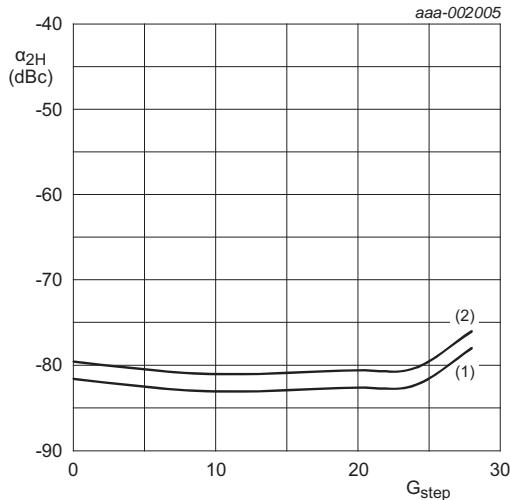
**Fig 28. Output third order intercept point as a function of output power per tone**



Tuned for  $f_{IF} = 450$  MHz.

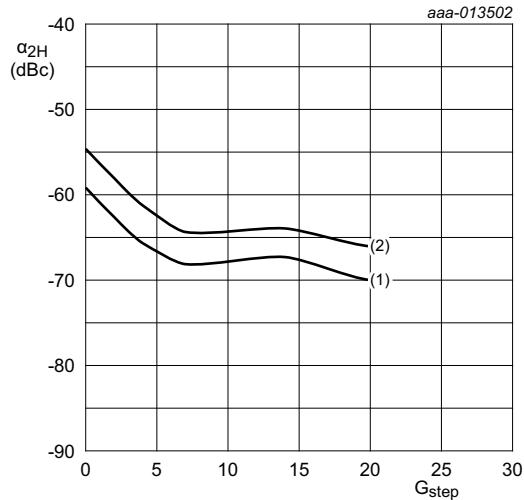
- (1) gain step 0
- (2) gain step 14

**Fig 29. Output third order intercept point as a function of output power per tone**



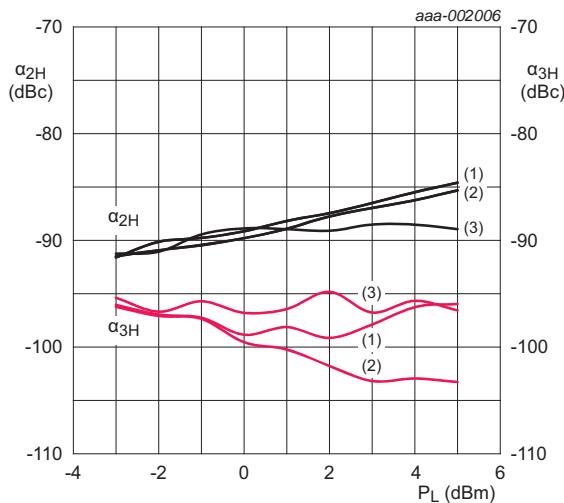
Tuned for  $f_{1F} = 86$  MHz;  $f_{2H} = 172$  MHz;  $f_{3H} = 258$  MHz.  
 (1)  $P_L = 2$  dBm  
 (2)  $P_L = 5$  dBm

**Fig 30. Second harmonic level as a function of gain step**



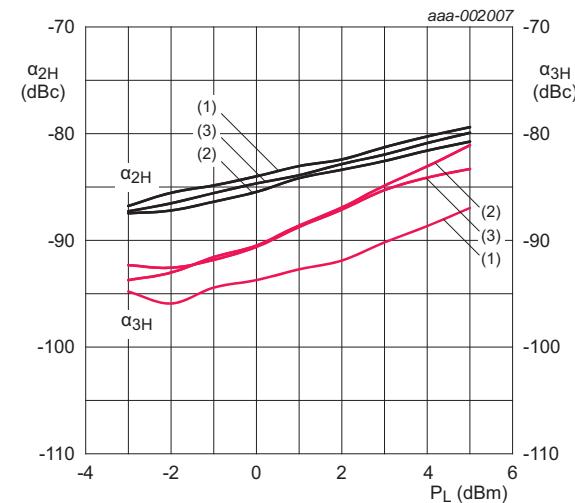
Tuned for  $f_{1F} = 225$  MHz;  $f_{2H} = 450$  MHz;  $f_{3H} = 675$  MHz.  
 (1)  $P_L = 2$  dBm  
 (2)  $P_L = 5$  dBm

**Fig 31. Second harmonic level as a function of gain step**



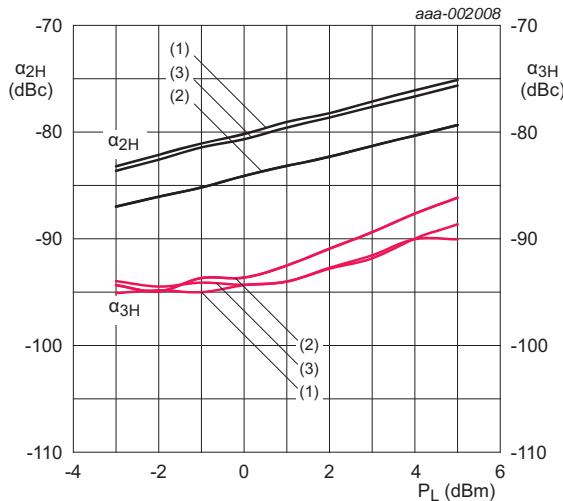
Tuned for  $f_{1F} = 50$  MHz;  $f_{2H} = 100$  MHz;  $f_{3H} = 150$  MHz;  
 $T_{amb} = 25$  °C.  
 (1) gain step 0  
 (2) gain step 14  
 (3) gain step 24

**Fig 32. Second harmonic level and third harmonic level as a function of output power**



Tuned for  $f_{1F} = 86$  MHz;  $f_{2H} = 172$  MHz;  $f_{3H} = 258$  MHz;  
 $T_{amb} = 25$  °C.  
 (1) gain step 0  
 (2) gain step 14  
 (3) gain step 24

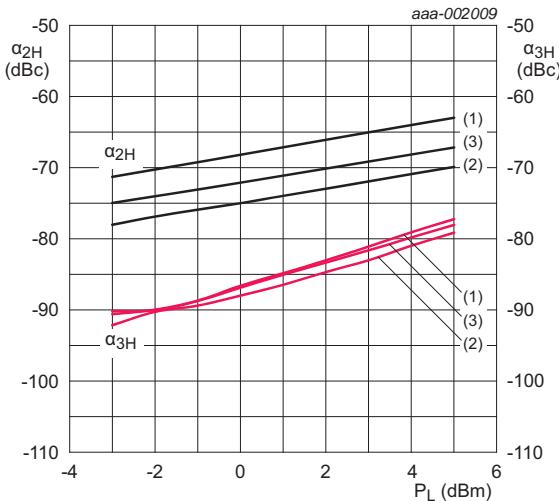
**Fig 33. Second harmonic level and third harmonic level as a function of output power**



Tuned for  $f_{IF} = 172$  MHz;  $f_{2H} = 358$  MHz;  $f_{3H} = 530$  MHz;  
 $T_{amb} = 25$  °C.

- (1) gain step 0
- (2) gain step 14
- (3) gain step 24

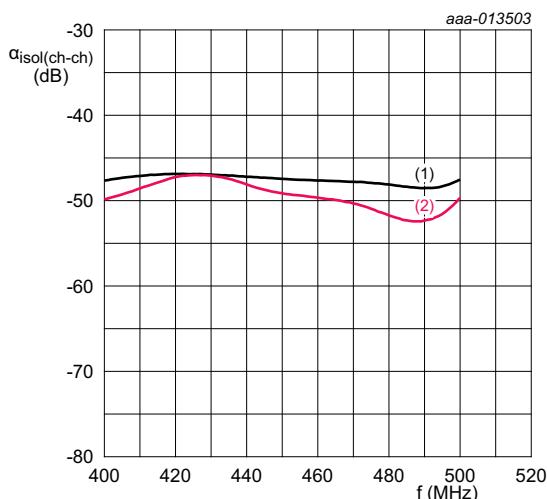
**Fig 34. Second harmonic level and third harmonic level as a function of output power**



Tuned for  $f_{IF} = 250$  MHz;  $f_{2H} = 500$  MHz;  $f_{3H} = 750$  MHz;  
 $T_{amb} = 25$  °C.

- (1) gain step 0
- (2) gain step 14
- (3) gain step 24

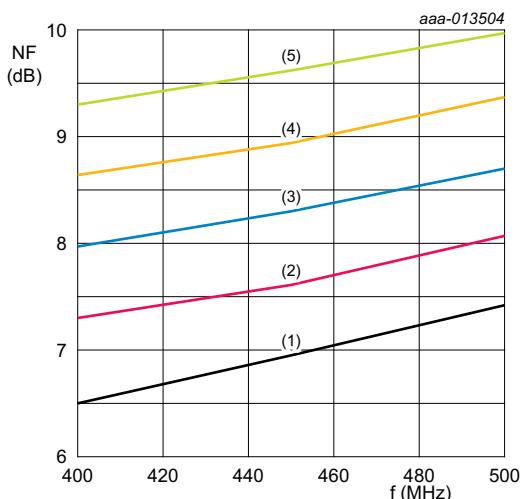
**Fig 35. Second harmonic level and third harmonic level as a function of output power**



Tuned for  $f_{IF} = 450$  MHz

- (1) channel A at gain step 0 (maximum gain);  
channel B at gain step 28 (minimum gain)
- (2) channel A at gain step 0 (maximum gain);  
channel B at gain step 0 (maximum gain)

**Fig 36. Isolation between channels as a function of frequency**

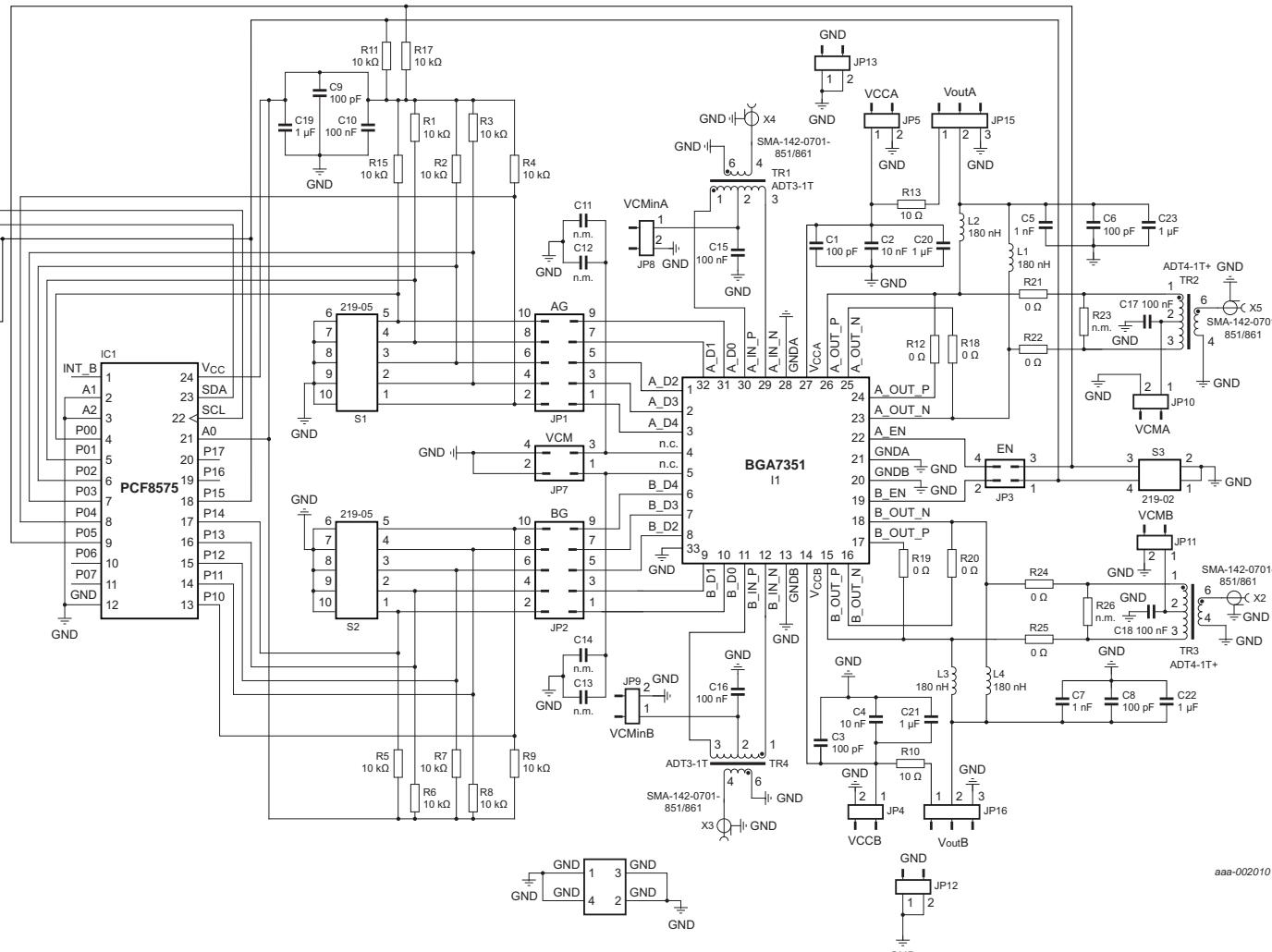


Tuned for  $f_{IF} = 450$  MHz

- (1) gain step 0
- (2) gain step 1
- (3) gain step 2
- (4) gain step 3
- (5) gain step 4

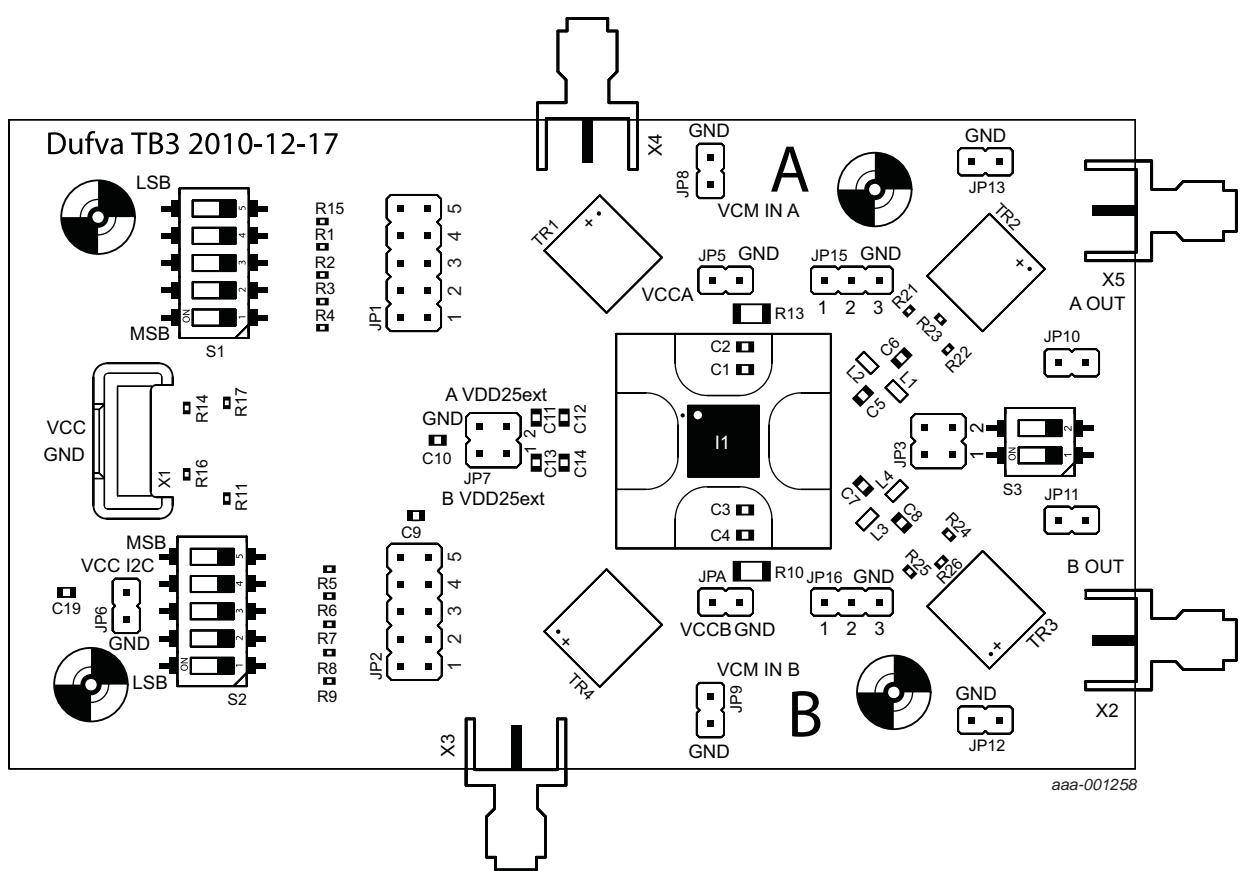
**Fig 37. Noise figure as a function of frequency**

## 1.1 Application PCB



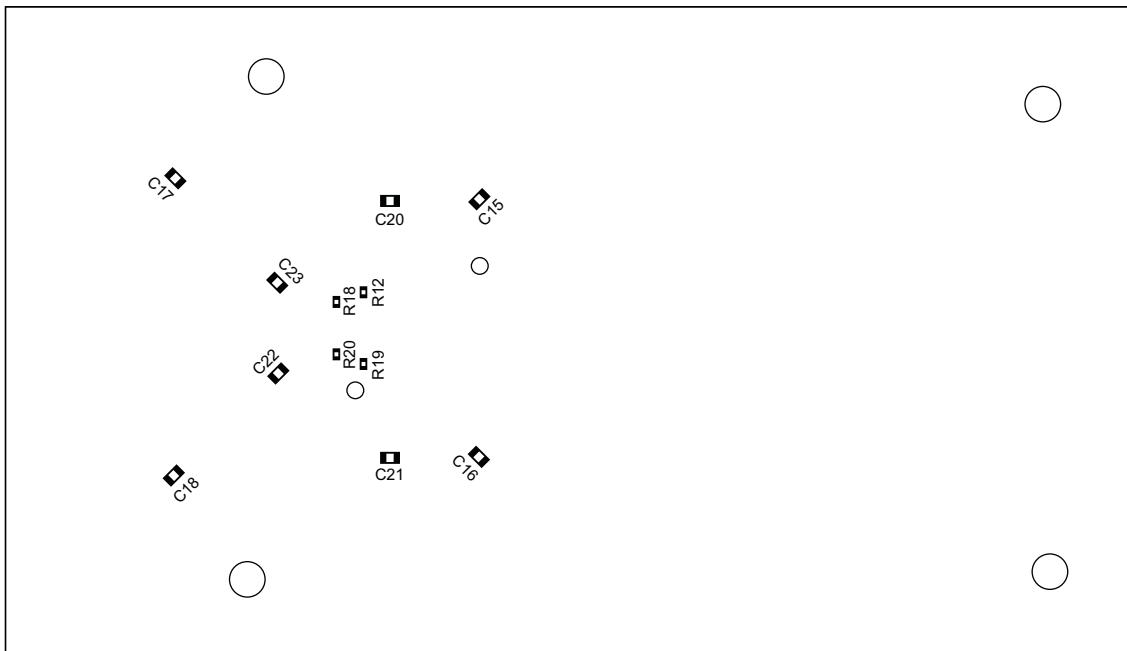
For a list of components see [Table 11](#).

**Fig 38. Schematic**



For a list of components see [Table 11](#).

Fig 39. Components top side



aaa-001259

For a list of components see [Table 11](#).

**Fig 40. Components bottom side**

**Table 11. List of components**

See [Figure 38](#), [Figure 39](#) and [Figure 40](#).

Component	Description	Conditions	Value	Size	Remarks
C1, C3, C6, C8, C9	capacitor		100 pF	0603	
C2, C4	capacitor		10 nF	0603	
C5, C7	capacitor		1 nF	0603	
C10, C15, C16, C17, C18	capacitor		100 nF	0603	
C11	capacitor		-	0603	not mounted
C12	capacitor		-	0603	not mounted
C13	capacitor		-	0603	not mounted
C14	capacitor		-	0603	not mounted
C19, C20, C21, C22, C23	capacitor		1 $\mu$ F	0603	
I1	BGA7351		-		
JP1	jumper		-	JP5	AG
JP2	jumper		-	JP5	BG
JP3	jumper		-	JP2	EN
JP4	jumper		-	JP2	VCCB
JP5	jumper		-	JP2	VCCA
JP6	jumper		-	JP2	VCCdig
JP7	jumper		-	JP2	VCM
JP8	jumper		-	JP2	VCMinA

**Table 11. List of components**See [Figure 38](#), [Figure 39](#) and [Figure 40](#).

Component	Description	Conditions	Value	Size	Remarks
JP9	jumper		-	JP2	VCMinB
JP10	jumper		-	JP2	VCMA
JP11	jumper		-	JP2	VCMB
JP12	jumper		-	JP2	GND
JP13	jumper		-	JP2	GND
JP15	jumper		-	JP3	VoutA
JP16	jumper		-	JP3	VoutB
L1, L2, L3, L4	inductor	$f_{IF} = 50$ MHz	1200 nH	0603	dependent on PCB layout
		$f_{IF} = 172$ MHz	150 nH	0603	dependent on PCB layout
		$f_{IF} = 250$ MHz	56 nH	0603	dependent on PCB layout
		$f_{IF} = 450$ MHz	27 nH	0603	dependent on PCB layout
R1, R2, R3, R4, R5, R6, R7, R8, R9, R11, R14, R15, R16, R17	resistor		10 k $\Omega$	0402	
R10, R13	resistor		10 $\Omega$	1206	
R12, R18, R19, R20, R21, R22, R24, R25	resistor		0 $\Omega$	0402	
R23, R26	resistor		-	0402	not mounted
S1, S2	DIP-switch		-		CTS-219-05
S3	DIP-switch		-		CTS-219-02
TR1	1:3 transformer		-		Mini Circuits ADT3-1T+
TR2	1:4 transformer		-		Mini Circuits ADT4-1T+
TR3	1:3 transformer		-		Mini Circuits ADT4-1T+
TR4	1:4 transformer		-		Mini Circuits ADT3-1T+
X1	-		-		not mounted
X2	SMA-connector		-		BOUT_P
X3	SMA-connector		-		BIN_P
X4	SMA-connector		-		AIN_P
X5	SMA-connector		-		AOUT_P

## 12. Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads;  
32 terminals; body 5 x 5 x 0.85 mm

SOT617-1

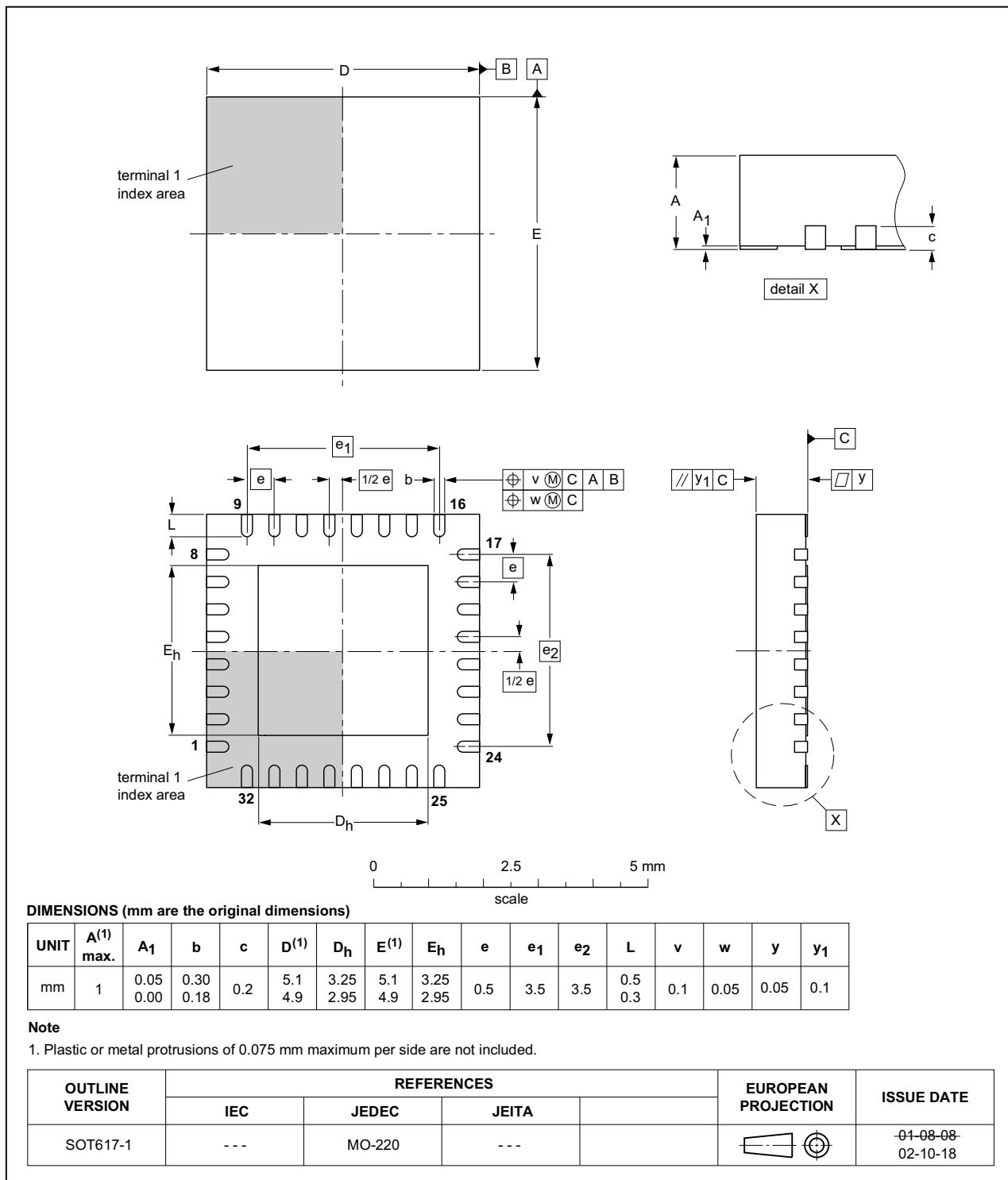


Fig 41. Package outline SOT617-1 (HVQFN32)

## 13. Abbreviations

**Table 12. Abbreviations**

Acronym	Description
ADC	Analog-to-Digital Converter
DIP	Dual In-line Package
EMI	ElectroMagnetic Interference
ESD	ElectroStatic Discharge
GSM	Global System for Mobile Communications
HTOL	High Temperature Operating Life
HVQFN	Heatsink Very-thin Quad Flat-pack No-leads
IF	Intermediate Frequency
LSB	Least Significant Bit
LTE	Long Term Evolution
MMIC	Monolithic Microwave Integrated Circuit
MSB	Most Significant Bit
PCB	Printed-Circuit Board
SMA	SubMiniature version A
WiMAX	Worldwide Interoperability for Microwave Access
W-CDMA	Wideband Code Division Multiple Access

## 14. Revision history

**Table 13. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGA7351 v.3	20140611	Product data sheet	-	BGA7351 v.2
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Table 8 on page 7</a>: some changes have been made</li> <li>• <a href="#">Section 11 on page 11</a>: some graphs have been added.</li> <li>• <a href="#">Table 11 on page 22</a>: the condition <math>f = 450</math> MHz has been added for the row containing the inductors</li> </ul>			
BGA7351 v.2	20121219	Product data sheet	-	BGA7351 v.1
BGA7351 v.1	20111228	Product data sheet	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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